



PATENT

Case Docket No. MICRON.170A

Date: October 7, 2002

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In re application of : Paul A. Farrar)
App. No. : 09/909,181)
Filed : July 19, 2001)
For : METHOD OF USING)
FOAMED INSULATORS IN)
THREE DIMENSIONAL)
MULTICHIP STRUCTURES)
Examiner : Chris C. Chu)
Art Unit : 2815)

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October 7, 2002

(Date)

Linda H. Lin, Reg. No. 51,240

UNITED STATES PATENT AND TRADEMARK OFFICE
P.O. Box 2327
Arlington, VA 22202

Sir:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated as shown below:

CLAIMS AS FILED						
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims	26	—	32	= 0 ×	\$18	= \$0
Independent Claims	2	—	3	= 0 ×	\$84	= \$0
If application has been amended to contain multiple dependent claim(s), then add					\$280	= \$0
Time Extension Fee						\$0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$0

(X) Submission of Proposed Drawing Amendment for Approval by Examiner with 1-sheet of marked drawings

(X) Return prepaid postcard.

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- (X) Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.
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